

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of:

Kouichi Takahashi, et al.

Application No.: 09/590,897

Filed: June 9, 2000

For: SEALING STRUCTURE FOR  
MULTI-CHIP MODULE

Customer No.: 20350

Confirmation No. 1657

Examiner: James M. Mitchell

Technology Center/Art Unit: 2813

AMENDMENT

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

August 14, 2008 (e-filed)

Sir:

In response to the Office Action mailed April 21, 2008, please enter the following amendments and remarks:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 4 of this paper.